

# N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	$R_{DS(on)}(\Omega)$ $I_{D}(A)$			
30	0.0039 at V <sub>GS</sub> = 10 V	107 <sup>d</sup>	67		
30	0.0045 at V <sub>GS</sub> = 4.5 V	103 <sup>d</sup>	07		

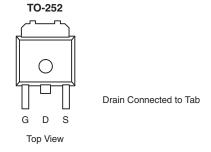
#### **FEATURES**

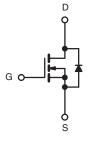
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>q</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

## ROHS COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

- DC/DC Converters
  - Synchronous Buck Low Side





Ordering Information: SUD42N03-3m9P-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C (Silicon Limited)		107 <sup>d</sup>	
Continuous Drain Current	T <sub>C</sub> = 70 °C (Silicon Limited)	I <sub>D</sub>	85 <sup>d</sup>	
	T <sub>C</sub> = 25 °C (Package Limited)		42	Α
Pulsed Drain Current (t = 300 μs)	I <sub>DM</sub>	120		
Avalanche Current	I <sub>AS</sub>	45		
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	101	mJ
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	В	73.5 <sup>b</sup>	w
waximum Fower Dissipation	T <sub>A</sub> = 25 °C <sup>c</sup>	P <sub>D</sub>	2.5	
Operating Junction and Storage Tem	T <sub>J</sub> , T <sub>sta</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	50	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	1.7			

#### Notes

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 42 A.



# N-Channel 30 V (D-S) MOSFET

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$ 30			V		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		2.5	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			1	-	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			50		
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
Drain Source On State Resistance	Б	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 22 A		0.0032	0.0039	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0037	0.0045		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		110		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			3535		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$		680			
Reverse Transfer Capacitance	C <sub>rss</sub>			400			
Total Gate Charge <sup>c</sup>	Qg			67	100	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		10.5			
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			12.2			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	Hz 0.3		2.8	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			11	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		10	20		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		35	53	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			10	20		
Drain-Source Body Diode Ratings ar	nd Characteris	stics <sup>b</sup> T <sub>C</sub> = 25 °C					
Continuous Current	I <sub>S</sub>				42	۸	
Pulsed Current	I <sub>SM</sub>				120	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V		0.83	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			41	62	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	$I_F = 10 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		2	3	Α	
Reverse Recovery Charge	Q <sub>rr</sub>			40	60	nC	

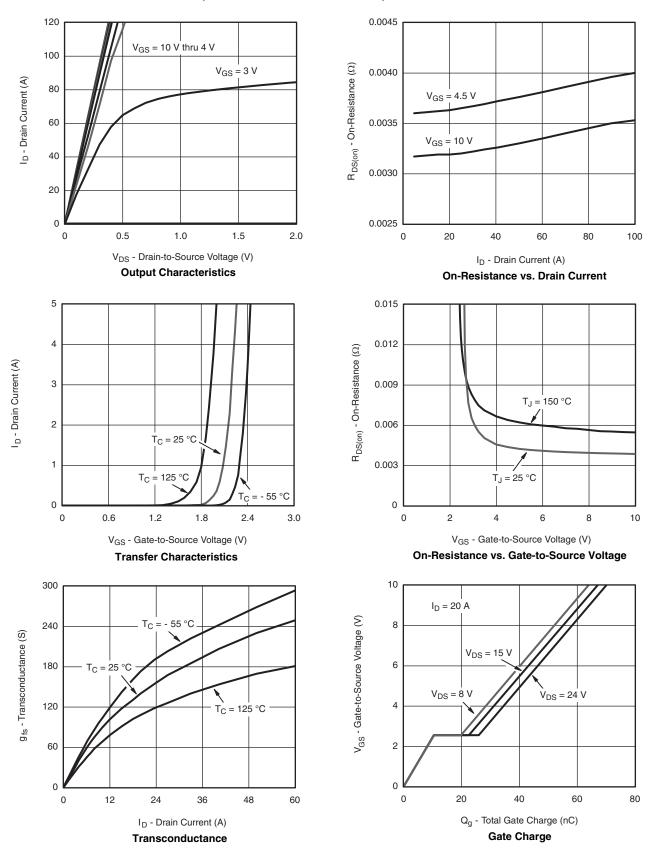
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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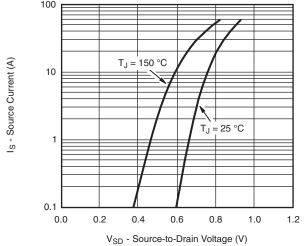
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

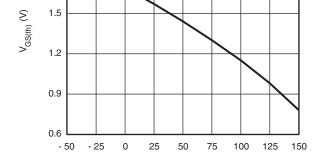


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### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

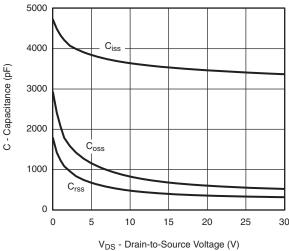


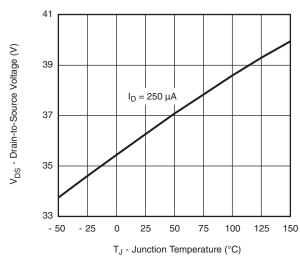


 $I_D = 250 \,\mu\text{A}$ 

#### Source-Drain Diode Forward Voltage



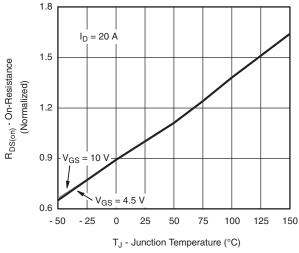


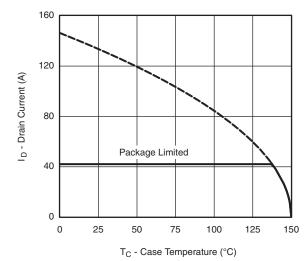




Capacitance

Drain Source Breakdown vs. Junction Temperature





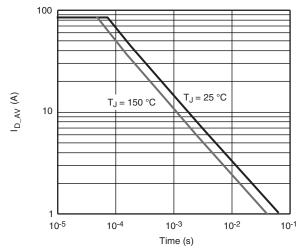
On-Resistance vs. Junction Temperature

**Current Derating** 

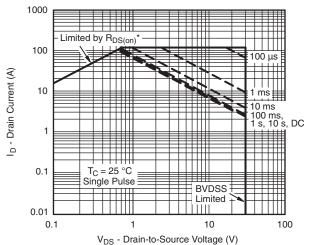


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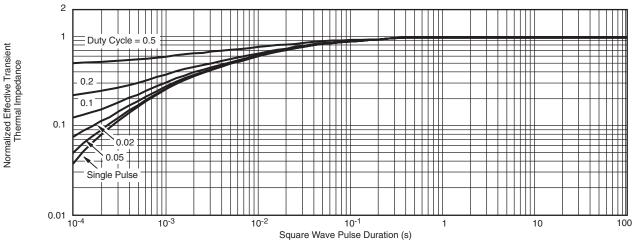
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Single Pulse Avalanche Current Capability vs. Time



\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified **Safe Operating Area** 

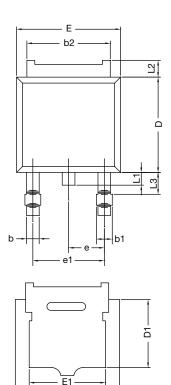


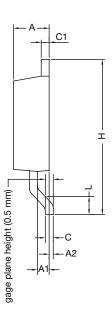
Normalized Thermal Transient Impedance, Junction-to-Case



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#### **TO-252AA CASE OUTLINE**





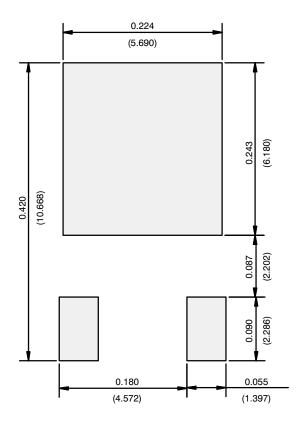
	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
A2	0.030	0.127	0.001	0.005	
b	0.71	0.88	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.44	0.206	0.214	
С	0.46	0.58	0.018	0.023	
C1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
D1	4.10	4.45	0.161	0.175	
Е	6.48	6.73	0.255	0.265	
E1	4.49	5.50	0.177	0.217	
е	2.28 BSC		0.090 BSC		
e1	4.57	4.57 BSC 0.180 BSC		BSC	
Н	9.65	10.41	0.380	0.410	
L	1.40	1.78	0.055	0.070	
L1	0.64	1.02	0.025	0.040	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.040	0.060	
ECN: T11-0110-Rev. L, 18-Apr-11 DWG: 5347					

#### Note

• Dimension L3 is for reference only.

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### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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